

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	600	photoresist with (lift off or liftoff) and polymer\$2 with substrate and metal	US-PGRUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/23 12:24
L2	189	photoresist with (lift off or liftoff) and polymer\$2 with substrate and metal and @PY<"2003"	US-PGRUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/23 12:24
L3	12	photoresist with (lift off or liftoff) and polymer\$2 with substrate and metal and develop\$3 with (solvent or mechanical\$3) and dry with (oven or IR or hot gas\$2 or microwave or roller) and @PY<"2003"	US-PGRUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/23 12:25
L4	0	photoresist with (lift off or liftoff) and flexible with substrate and metal and develop\$3 with (solvent or mechanical\$3) and dry with (oven or IR or hot gas\$2 or microwave or roller) and @PY<"2003"	US-PGRUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/23 12:34
L5	0	photoresist with (lift off or liftoff) and flexible with substrate and metal and develop\$3 with (solvent or mechanical\$3) and dry with (oven or IR or hot gas\$2 or microwave or roller) and @PY<"2004"	US-PGRUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/23 12:34
L6	73	photoresist with (lift off or liftoff) and flexible with substrate and metal and develop\$3 and @PY<"2004"	US-PGRUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/23 12:34
L7	1721	(lithography or photoresist) with (lift off or liftoff) and (polymer\$2 or metal\$3 or glass or metal oxide) with substrate and @PY<"2004"	US-PGRUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/23 13:42
L8	132	(lithography or photoresist) with (lift off or liftoff) and (polymer\$2 or metal\$3 or glass or metal oxide) with substrate and (sputter or evaporate) with (metal or half-metal) and @PY<"2004"	US-PGRUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/23 13:43
L9	265	427/98.5.cds.	US-PGRUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/23 14:01

L10	95	427/98.5.cds. and (resist or photoinitiator)	US-PGRUB; USPAT; FPRS; EPO; JPO; DERVENT; IBM_TDB	ADJ	ON	2009/02/23 14:02
L11	26	427/98.5.cds. and (resist or photoinitiator) and plasma	US-PGRUB; USPAT; FPRS; EPO; JPO; DERVENT; IBM_TDB	ADJ	ON	2009/02/23 14:03
S1	1	(*6548121*).PN	USPAT; USCOR	OR	OFF	2009/02/19 16:58
S2	1180	"ciba specialty chemicals corporation" as.	US-PGRUB; USPAT; FPRS; EPO; JPO; DERVENT; IBM_TDB	ADJ	ON	2009/02/19 18:03
S3	5	"ciba specialty chemicals corporation" as. and strongly adherent coatings	US-PGRUB; USPAT; FPRS; EPO; JPO; DERVENT; IBM_TDB	ADJ	ON	2009/02/19 18:04
S4	5	"ciba specialty chemicals corporation" as. and strongly adherent coating	US-PGRUB; USPAT; FPRS; EPO; JPO; DERVENT; IBM_TDB	ADJ	ON	2009/02/19 18:04
S5	1	10/566743 app.	US-PGRUB; USPAT; FPRS; EPO; JPO; DERVENT; IBM_TDB	ADJ	ON	2009/02/19 18:37
S6	1	(*7455891*).PN	USPAT; USCOR	OR	OFF	2009/02/20 11:00
S7	8	(*("7455891") or (*6251963*) or (*6486228*) or (*6515051*) or (*6803392*) or (*6733847*) or (*6548121*) or (*6368362*)) .PN	USPAT; USCOR	OR	OFF	2009/02/20 11:09
S8	9	(*("7455891") or (*6251963*) or (*6486228*) or (*6515051*) or (*6803392*) or (*6733847*) or (*6548121*) or (*6368362*) or (*6399805*).PN	USPAT; USCOR	OR	OFF	2009/02/20 11:14
S9	108	*366951* *3936305* *4082679* *4199421* *4226763* *4246315* *4275004* *4278589* *4292152* *4298738* *4315848* *4324744* *4347180* *4385109* *4466939* *4533652* *4567106* *4681905* *4684679* *4684680* *4710523* *4757593* *4792632* *4861916* *4868246* *4965294* *4990364* *5053246* *5080944* *5106891* *5108835* *5116534* *5153284* *5166355* *5168087* *5196142* *5218009* *5250698* *5252403* *5278314* *5280124* *5292890* *5330539* *5360850* *5399770* *5436349* *5456726* *547292* *5504236* *5516914* *5549847* *5584760* *5586342* *5574166* *5617987* *5646088* *5935900* *5942290* *5955514* *5990189* *6099122* *6190423* *6329445* *6344505* *6361925* *6376065* *6399805* *6407254* *6548121* *6733847*.PN. OR(*6251963* *6368362* *6399805* *6486228* *6515051* *6548121* *6733847* *7455891*).URPN	US-PGRUB; USPAT; USCOR	ADJ	ON	2009/02/20 11:21
S10	15	*4199421* *4246315* *4466939* *4567106* *4990364* *5053246* *5252403* *6099122* *6548121* *6733847*.PN OR(*6548121* *6733847* *7455891*).URPN	US-PGRUB; USPAT; USCOR	ADJ	ON	2009/02/20 11:22
S11	21169	427/593,535,536,517,407,1-412,5,532- 559,517,509,512,513,517,518,519,520,535,536,538,551,563,554,556,407,2,409,412,412,1,419,2.cds. or 430/311.cds.	US-PGRUB; USPAT; FPRS; EPO; JPO; DERVENT; IBM_TDB	ADJ	ON	2009/02/20 11:27

S12	5299	427/533,509.cds. or 430/311.cds.	US_PGRUB; USPAT; FFPS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 11:27
S13	211	adhere\$4 or adhesion or glu\$3 or bond\$3) with metallized with (organic or polymer) with substrate	US_PGRUB; USPAT; FFPS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 12:30
S14	139	adhere\$4 or adhesion or glu\$3 or bond\$3) with metallized with (organic or polymer) with substrate and @PY<2004"	US_PGRUB; USPAT; FFPS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 12:30
S15	13	adhere\$4 or adhesion or glu\$3 or bond\$3) with metallized with (organic or polymer) with substrate and @PY<2004" and S11	US_PGRUB; USPAT; FFPS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 12:30
S16	7	circuit and photoinitiator with adhesion with metal	US_PGRUB; USPAT; FFPS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 16:56
S17	163	circuit and photoinitiator with adhesion and (metal or copper)	US_PGRUB; USPAT; FFPS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 17:11
S18	13	circuit and photoinitiator with adhesion with (metal or copper)	US_PGRUB; USPAT; FFPS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 17:11
S19	613	circuit and photoresist with adhesion with (metal or copper)	US_PGRUB; USPAT; FFPS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 17:18
S20	283	circuit and photoresist with adhesion with (metal or copper) and plasma	US_PGRUB; USPAT; FFPS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 17:18
S21	47	circuit and photoresist with adhesion with (metal or copper) with plasma	US_PGRUB; USPAT; FFPS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 17:19

S22	0	solder mask with (photopolymerizable or photoresist or photoinitiator or light sensitive or crosslink\$3 or UV) with adhesion with (metal or copper) with plasma	US-PGRUB; USPAT; FFRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 17:34
S23	0	solder mask with (photopolymerizable or photoresist or photoinitiator or light sensitive or crosslink\$3 or UV) and adhesion with (metal or copper) with plasma	US-PGRUB; USPAT; FFRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 17:34
S24	1116	solder mask with (photopolymerizable or photoresist or photoinitiator or light sensitive or crosslink\$3 or UV)	US-PGRUB; USPAT; FFRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 17:35
S25	46	solder mask with (photopolymerizable or photoresist or photoinitiator or light sensitive or crosslink\$3 or UV) with adhesion	US-PGRUB; USPAT; FFRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 17:35
S26	10	solder mask with UV with adhesion	US-PGRUB; USPAT; FFRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 17:40
S27	2	"20030129322" did.	US-PGRUB; USPAT; FFRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 17:42
S28	13	solder mask with (cvd or evaporate or pvd)	US-PGRUB; USPAT; FFRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 18:38
S29	692	solder with (cvd or evaporate or pvd)	US-PGRUB; USPAT; FFRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 18:41
S30	5	solder with (cvd or evaporate or pvd) with (photopolymerizable or UV or photoinitiator or photoresist)	US-PGRUB; USPAT; FFRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 18:43
S31	149	solder with (cvd or evaporate or pvd) and (photopolymerizable or UV or photoinitiator or photoresist)	US-PGRUB; USPAT; FFRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 18:44

S32	12645	metal with (cvd or evaporate or pvd) and (photopolymerizable or UV or photoinitiator or photoresist)	US-PGRUB; USPAT; FPIRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 18:44
S33	45	solder with (cvd or evaporate or pvd) and (photopolymerizable or UV or photoinitiator or photoresist) and @PY<"2004"	US-PGRUB; USPAT; FPIRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 18:44
S34	580	circuit board and (metal or solder or contact or electrode or copper) with (cvd or evaporate or pvd) and (photopolymerizable or UV or photoinitiator or photoresist) and @PY<"2004"	US-PGRUB; USPAT; FPIRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 18:57
S35	25	circuit board and (metal or solder or contact or electrode or copper) with (cvd or evaporate or pvd) with (photopolymerizable or UV or photoinitiator or photoresist) and @PY<"2004"	US-PGRUB; USPAT; FPIRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 18:57
S36	3	wiring board and (metal or solder or contact or electrode or copper) with (cvd or evaporate or pvd) with (photopolymerizable or UV or photoinitiator or photoresist) and @PY<"2004"	US-PGRUB; USPAT; FPIRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 18:58
S37	121	circuit board and (metal or solder or contact or electrode or copper) with (cvd or evaporate or pvd) and (photopolymerizable or UV or photoinitiator or photoresist) and @PY<"2004" and cmp	US-PGRUB; USPAT; FPIRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 19:05
S38	1	(*6524950*), PN.	USPAT; USOOR	OR	OFF	2009/02/20 19:21

2/23/2009 3:01:12 PM

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